

ADG736* PRODUCT PAGE QUICK LINKS

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EVALUATION KITS

- Evaluation Board for 10-Lead MSOP Devices in the Switches and Multiplexers Portfolio

DOCUMENTATION

Data Sheet

- ADG736: CMOS Low Voltage 2.5 Ω Dual SPDT Switch Data Sheet

User Guides

- UG-1037: Evaluation Board for 10-Lead MSOP Devices in the Switches and Multiplexers Portfolio

REFERENCE MATERIALS

Product Selection Guide

- Switches and Multiplexers Product Selection Guide

Technical Articles

- CMOS Switches Offer High Performance in Low Power, Wideband Applications
- Data-acquisition system uses fault protection
- Enhanced Multiplexing for MEMS Optical Cross Connects
- Temperature monitor measures three thermal zones

DESIGN RESOURCES

- ADG736 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

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REVISION HISTORY

2/12—Rev. C to Rev. D

Added Automotive Information (Throughout)	1
Updated Outline Dimensions	12
Changes to Ordering Guide	12

12/07—Rev. B to Rev. C

Updated Temperature Range (Throughout)	1
Changes to Features Section.....	1
Changes to Figure 4 and Figure 5	7
Changes to Ordering Guide	12

1/07—Rev. A to Rev. B

Updated Format.....	Universal
Changes to Leakage Currents	3
Changes to Leakage Currents	4
Changes to Ordering Guide	12
Updated Outline Dimensions	12

11/03—Rev. 0 to Rev. A

Renumbered Figures and TPCs	Universal
Change to Title.....	1
Changes to Applications	1
Changes to Absolute Maximum Ratings	4
Changes to Ordering Guide	4
Changes to Test Circuit 3.....	7
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SPECIFICATIONS

$V_{DD} = 5\text{ V} \pm 10\%$, $GND = 0\text{ V}$. All specifications -40°C to $+125^{\circ}\text{C}$, unless otherwise noted.

Table 1.

Parameter	B Version			Unit	Test Conditions/Comments
	25°C	-40°C to $+85^{\circ}\text{C}$	-40°C to $+125^{\circ}\text{C}$		
ANALOG SWITCH					
Analog Signal Range			0 V to V_{DD}	V	$V_S = 0\text{ V}$ to V_{DD} , $I_{DS} = -10\text{ mA}$; see Figure 10
On Resistance (R_{ON})	2.5			Ω typ	
	4	4.5	7	Ω max	$V_S = 0\text{ V}$ to V_{DD} , $I_{DS} = -10\text{ mA}$
On Resistance Match Between Channels (ΔR_{ON})	0.1			Ω typ	
		0.4	0.4	Ω max	$V_S = 0\text{ V}$ to V_{DD} , $I_{DS} = -10\text{ mA}$
On Resistance Flatness ($R_{FLAT(ON)}$)	0.5			Ω typ	
		1.2	1.5	Ω max	
LEAKAGE CURRENTS					$V_{DD} = 5.5\text{ V}$
Source Off Leakage I_S (Off)	± 0.01		1	nA typ	$V_S = 4.5\text{ V}/1\text{ V}$, $V_D = 1\text{ V}/4.5\text{ V}$; see Figure 11
Channel On Leakage I_D , I_S (On)	± 0.01		5	nA typ	$V_S = V_D = 1\text{ V}$ or 4.5 V ; see Figure 12
DIGITAL INPUTS					
Input High Voltage, V_{INH}		2.4	2.4	V min	$V_{IN} = V_{INL}$ or V_{INH}
Input Low Voltage, V_{INL}		0.8	0.8	V max	
Input Current, I_{INL} or I_{INH}	0.005			μA typ	
		± 0.1	± 0.1	μA max	
DYNAMIC CHARACTERISTICS ¹					
t_{ON}	12			ns typ	$R_L = 300\ \Omega$, $C_L = 35\text{ pF}$
		16	16	ns max	$V_S = 3\text{ V}$; see Figure 13
t_{OFF}	5			ns typ	$R_L = 300\ \Omega$, $C_L = 35\text{ pF}$
		8	8	ns max	$V_S = 3\text{ V}$; see Figure 13
Break-Before-Make Time Delay, t_D	7			ns typ	$R_L = 300\ \Omega$, $C_L = 35\text{ pF}$
		1	1	ns min	$V_{S1} = V_{S2} = 3\text{ V}$; see Figure 14
Off Isolation	-62			dB typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 10\text{ MHz}$
	-82			dB typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 15
Channel-to-Channel Crosstalk	-62			dB typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 10\text{ MHz}$
	-82			dB typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 16
Bandwidth (-3 dB)	200			MHz typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$; see Figure 17
C_S (Off)	9			pF typ	
C_D , C_S (On)	32			pF typ	
POWER REQUIREMENTS					$V_{DD} = 5.5\text{ V}$
I_{DD}	0.001			μA typ	Digital inputs = 0 V or 5 V
		1.0	1.0	μA max	

¹ Guaranteed by design; not subject to production test.

$V_{DD} = 3\text{ V} \pm 10\%$, $GND = 0\text{ V}$. All specifications -40°C to $+125^{\circ}\text{C}$, unless otherwise noted.

Table 2.

Parameter	B Version			Unit	Test Conditions/Comments
	25°C	−40°C to +85°C	−40°C to +125°C		
ANALOG SWITCH					
Analog Signal Range	5	5.5	0 V to V _{DD}	V	V _S = 0 V to V _{DD} , I _{DS} = −10 mA; see Figure 10
On Resistance (R _{ON})				Ω typ	
On Resistance Match Between Channels (ΔR _{ON})	0.1	8	12	Ω max	See Figure 10
		Ω typ	V _S = 0 V to V _{DD} , I _{DS} = −10 mA		
On Resistance Flatness (R _{FLAT (ON)})		0.4	0.4	Ω max	V _S = 0 V to V _{DD} , I _{DS} = −10 mA
		2.5	2.5	Ω typ	
LEAKAGE CURRENTS					
Source Off Leakage I _S (Off)	±0.01		1	nA typ	V _{DD} = 3.3 V V _S = 3 V/1 V, V _D = 1 V/3 V; see Figure 11
Channel On Leakage I _D , I _S (On)	±0.01		5	nA typ	V _S = V _D = 1 V or 3 V; see Figure 12
DIGITAL INPUTS					
Input High Voltage, V _{INH}	0.005	2.0	2.4	V min	V _{IN} = V _{INL} or V _{INH}
Input Low Voltage, V _{INL}		0.4	0.8	V max	
Input Current, I _{INL} or I _{INH}		±0.1	± 0.1	μA typ	
				μA max	
DYNAMIC CHARACTERISTICS ¹					
t _{ON}	14	20	20	ns typ	R _L = 300 Ω, C _L = 35 pF
				ns max	V _S = 2 V; see Figure 13
t _{OFF}	6	10	10	ns typ	R _L = 300 Ω, C _L = 35 pF
				ns max	V _S = 2 V; see Figure 13
Break-Before-Make Time Delay, t _D	7	1	1	ns typ	R _L = 300 Ω, C _L = 35 pF
				ns min	V _{S1} = V _{S2} = 2 V; see Figure 14
Off Isolation	−62			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 10 MHz
	−82			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 15
Channel-to-Channel Crosstalk	−62			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 10 MHz
	−82			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 16
Bandwidth (−3 dB)	200			MHz typ	R _L = 50 Ω, C _L = 5 pF; see Figure 17
C _S (Off)	9			pF typ	
C _D , C _S (On)	32			pF typ	
POWER REQUIREMENTS					
I _{DD}	0.001			μA typ	V _{DD} = 3.3 V Digital inputs = 0 V or 3 V
		1.0	1.0	μA max	

¹ Guaranteed by design; not subject to production test.

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 3.

Parameter	Rating
V_{DD} to GND	$-0.3\text{ V to }+6\text{ V}$
Analog, Digital Inputs ¹	$-0.3\text{ V to }V_{DD} + 0.3\text{ V}$ or 30 mA, whichever occurs first
Continuous Current, S or D	30 mA
Peak Current, S or D	100 mA (Pulsed at 1 ms, 10% duty cycle maximum)
Operating Temperature Range	
Automotive	$-40^\circ\text{C to }+125^\circ\text{C}$
Storage Temperature Range	$-65^\circ\text{C to }+150^\circ\text{C}$
Junction Temperature	150°C
MSOP Package, Power Dissipation	315 mW
θ_{JA} Thermal Impedance	205°C/W
Lead Temperature (Soldering, 10 sec)	300°C
IR Reflow (Peak Temperature, <20 sec)	235°C
Lead-Free Reflow Soldering	
Peak Temperature	$260(+0/-5)^\circ\text{C}$
Time at Peak Temperature	10 sec to 40 sec
ESD	2 kV

¹ Overvoltages at IN, S, or D are clamped by internal diodes. Current should be limited to the maximum ratings given.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

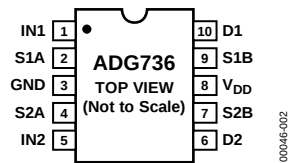


Figure 2. Pin Configuration

Table 4. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	IN1	Logic Control Input.
2	S1A	Source Terminal. May be an input or output.
3	GND	Ground (0 V) Reference.
4	S2A	Source Terminal. May be an input or output.
5	IN2	Logic Control Input.
6	D2	Drain Terminal. May be an input or output.
7	S2B	Source Terminal. May be an input or output.
8	V _{DD}	Most Positive Power Supply Potential.
9	S1B	Source Terminal. May be an input or output.
10	D1	Drain Terminal. May be an input or output.

Table 5. Truth Table

Logic	Switch A	Switch B
0	Off	On
1	On	Off

TYPICAL PERFORMANCE CHARACTERISTICS

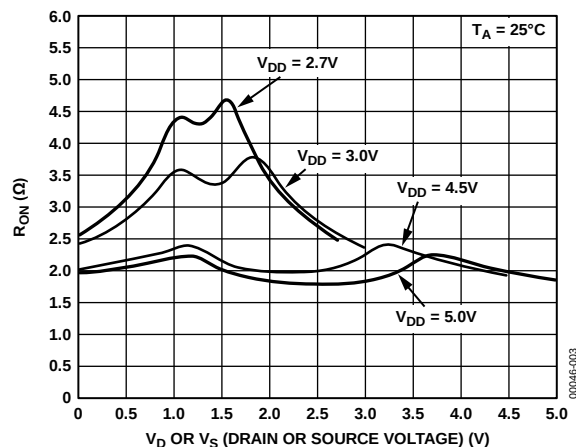
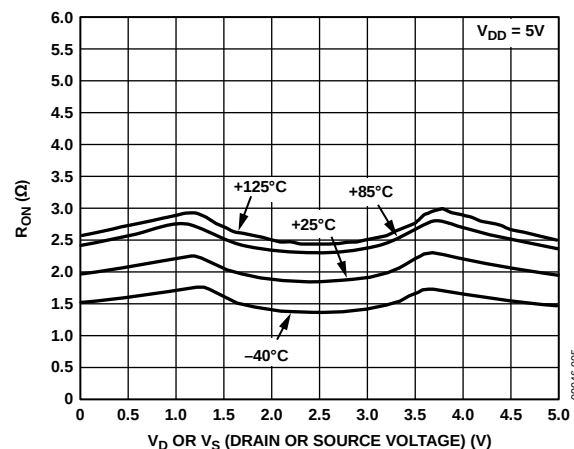
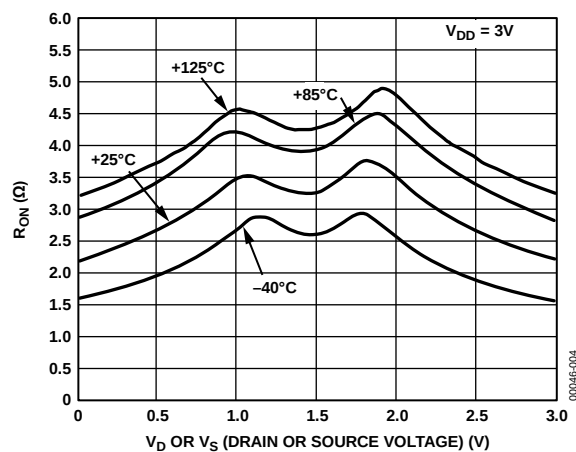
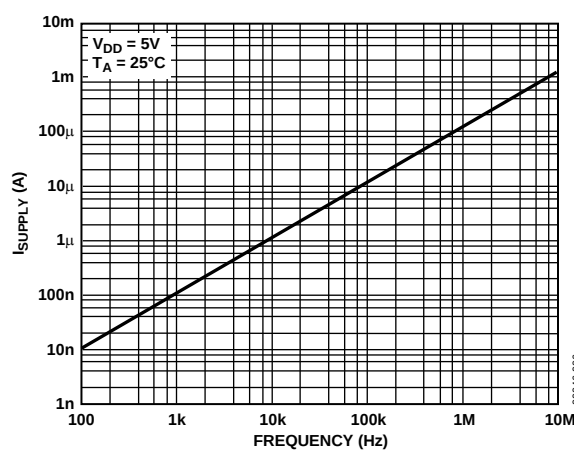
Figure 3. On Resistance as a Function of V_D or V_S Single SuppliesFigure 5. On Resistance as a Function of V_D or V_S for Different Temperatures
 $V_{DD} = 5V$ Figure 4. On Resistance as a Function of V_D or V_S for Different Temperatures
 $V_{DD} = 3V$ 

Figure 6. Supply Current vs. Input Switching Frequency

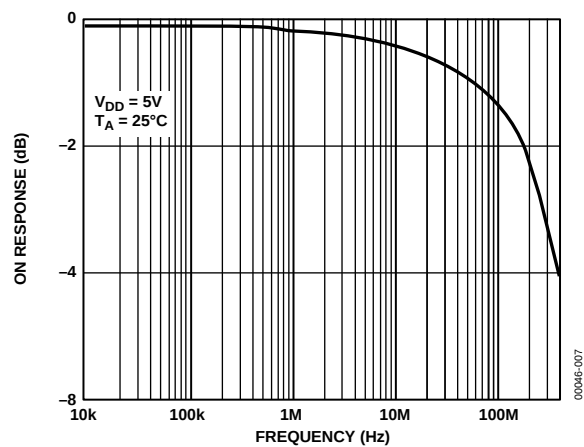


Figure 7. Bandwidth

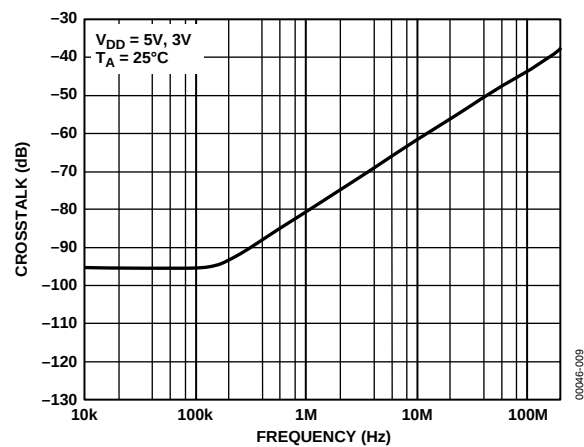


Figure 9. Crosstalk vs. Frequency

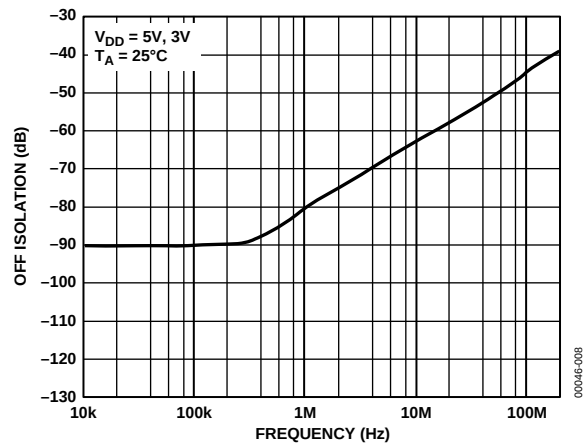


Figure 8. Off Isolation vs. Frequency

TEST CIRCUITS

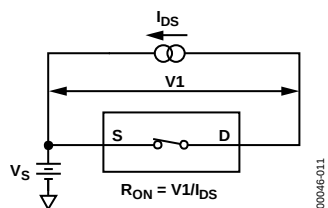


Figure 10. On Resistance

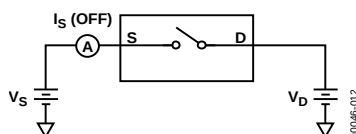


Figure 11. Off Leakage

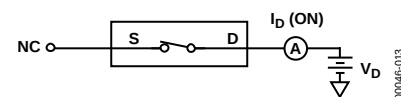


Figure 12. On Leakage

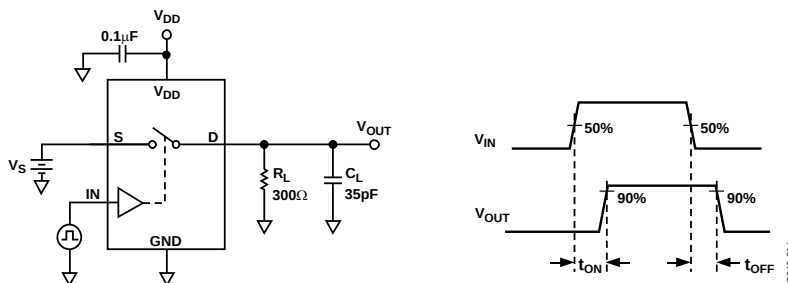


Figure 13. Switching Times

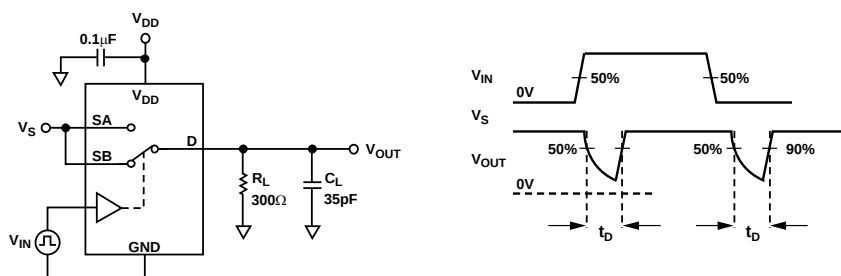
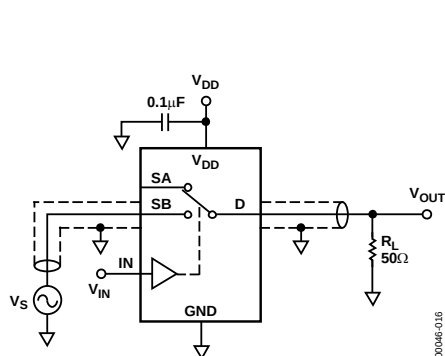
Figure 14. Break-Before-Make Time Delay, t_D 

Figure 15. Off Isolation

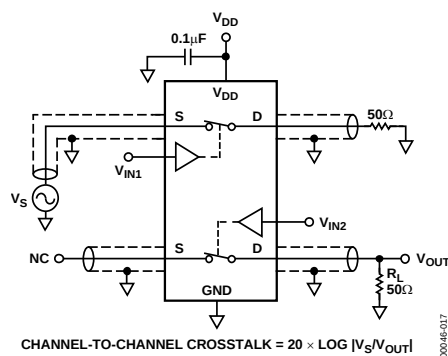


Figure 16. Channel-to-Channel Crosstalk

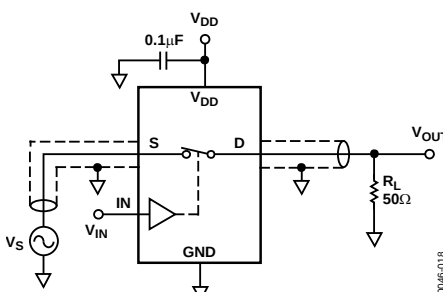


Figure 17. Bandwidth

TERMINOLOGY

 R_{ON}

Ohmic resistance between Terminal D and Terminal S.

 ΔR_{ON}

On resistance match between any two channels; that is, R_{ON} maximum – R_{ON} minimum.

 $R_{FLAT (ON)}$

Flatness is defined as the difference between the maximum and minimum value of on resistance as measured over the specified analog signal range.

 I_s (Off)

Source leakage current with the switch off.

 I_D , I_s (On)

Channel leakage current with the switch on.

 V_D (V_s)

Analog voltage on Terminal D and Terminal S.

 C_s (Off)

Off switch source capacitance.

 C_D , C_s (On)

On switch capacitance.

 t_{ON}

Delay between applying the digital control input and the output switching on. See Figure 13.

 t_{OFF}

Delay between applying the digital control input and the output switching off. See Figure 13.

 t_D

Off time or on time measured between the 90% points of both switches, when switching from one address state to another. See Figure 14.

Crosstalk

A measure of unwanted signal that is coupled from one channel to another as a result of parasitic capacitance.

Off Isolation

A measure of unwanted signal coupling through an off switch.

Bandwidth

The frequency at which the output is attenuated by –3 dB.

On Response

The frequency response of the on switch.

On Loss

The voltage drop across the on switch, seen on the on response vs. frequency plot (see Figure 7) as how many decibels (dB) the signal is away from 0 dB at very low frequencies.

APPLICATIONS INFORMATION

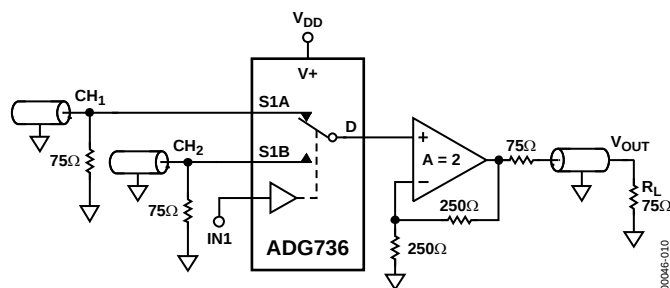
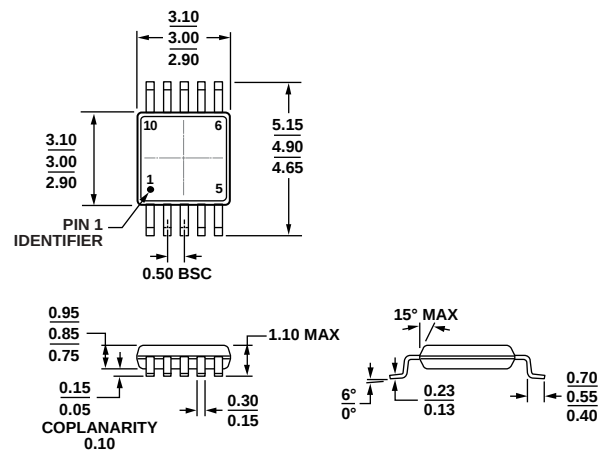


Figure 18. Using the ADG736 to Select Between Two Video Signals

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-187-BA
 Figure 19. 10-Lead Mini Small Outline Package [MSOP]
 (RM-10)
 Dimensions shown in millimeters

ORDERING GUIDE

Model ^{1,2}	Temperature Range	Package Description	Package Option	Branding
ADG736BRM	−40°C to +125°C	10-Lead Mini Small Outline Package (MSOP)	RM-10	SAB
ADG736BRM-REEL	−40°C to +125°C	10-Lead Mini Small Outline Package (MSOP)	RM-10	SAB
ADG736BRM-REEL7	−40°C to +125°C	10-Lead Mini Small Outline Package (MSOP)	RM-10	SAB
ADG736BRMZ	−40°C to +125°C	10-Lead Mini Small Outline Package (MSOP)	RM-10	SAB#
ADG736BRMZ-REEL	−40°C to +125°C	10-Lead Mini Small Outline Package (MSOP)	RM-10	SAB#
ADG736BRMZ-REEL7	−40°C to +125°C	10-Lead Mini Small Outline Package (MSOP)	RM-10	SAB#
ADW54010Z-OREEL	−40°C to +125°C	10-Lead Mini Small Outline Package (MSOP)	RM-10	SAB#

¹ Z = RoHS Compliant Part, # denotes RoHS compliant part may be top or bottom marked.

² W = Qualified for Automotive Applications.

AUTOMOTIVE PRODUCTS

The ADW54010Z model is available with controlled manufacturing to support the quality and reliability requirements of automotive applications. Note that these automotive models may have specifications that differ from the commercial models; therefore, designers should review the Specifications section of this data sheet carefully. Only the automotive grade products shown are available for use in automotive applications. Contact your local Analog Devices account representative for specific product ordering information and to obtain the specific Automotive Reliability reports for these models.